

RX Family

IRQ Module Using Firmware Integration Technology

Introduction

This application note describes the Interrupt Request (IRQ) module which uses Firmware Integration Technology (FIT). This module uses IRQ to provide a unified, abstracted interface for handling events from external pin interrupts. In this document, this module is referred to as the IRQ FIT module.

Target Devices

- RX110, RX111, RX113 Groups
- RX130 Group
- RX13T Group
- RX140 Group
- RX230 Group
- RX231 Group
- RX23T Group
- RX23W Group
- RX23E-A Group
- RX23E-B Group
- RX24T Group
- RX24U Group
- RX26T Group
- RX260, RX261 Group
- RX64M Group
- RX651, RX65N Group
- RX66T Group
- RX66N Group
- RX660 Group
- RX671 Group
- RX71M Group
- RX72T GroupRX72M Group
- RX72N Group

When using this application note with other Renesas MCUs, careful evaluation is recommended after making modifications to comply with the alternate MCU.

Target Compilers

- Renesas Electronics C/C++ Compiler Package for RX Family
- · GCC for Renesas RX
- IAR C/C++ Compiler for Renesas RX

For details of the confirmed operation contents of each compiler, refer to "6.1 Confirmed Operation Environment".

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1. Overview

1.1 IRQ FIT Module

The IRQ FIT module can be used by being implemented in a project as an API. See section 2.13, Adding the FIT Module to Your Project for details on methods to implement this FIT module into a project.

1.2 Overview of the IRQ FIT Module

This software provides a unified, abstracted interface for handling events from external pin interrupts. These events are mapped to the IRQ vectors. The operations needed to prepare the IRQs for handling interrupts are performed in the R_IRQ_Open() API function. IRQ vectors supported by each MCU can be used, so a means to identify a particular IRQ vector in each API function is provided. The software makes use of a data structure assigned to each IRQ that stores information specific to that vector required to perform the various IRQ API functions. One such data structure is allocated for each IRQ in use. Each of these data structures is referred to as an IRQ handle, and each has a handle pointer.

When an IRQ is initialized through the R_IRQ_Open() function, its handle pointer is returned to the caller. Thereafter, the application must provide the handle pointer for the selected IRQ when calling any of the remaining IRQ API functions. When called, the API functions extract the IRQ number from the handle, as well as other information linked to that IRQ and contained in the handle structure.

When an IRQ event is triggered, an interrupt handler is invoked that passes control to a user defined "Callback" function. Since Callbacks are executed in the interrupt state, further interrupts are disabled until the callback completes and the program returns from the ISR. Interrupt processing may be enabled or disabled by the user application at any time after the IRQ vector has been initialized.

User application code: callback functions

FIT IRQ Support Module
FIT BSP

RX MCU GPIO Input

Figure 1 : Example Figure Showing Project Layers

1.3 Using the FIT IRQ module

The primary use of the IRQ module is to make it easy to generate interrupt events that are triggered by a change in state of an MCU GPIO input pin. The user's application can arbitrarily assign a callback function to the event that will execute upon event detection.

After adding the IRQ module to your project you will need to modify the r irg rx config.h file to configure the software for your installation.

If Smart Configurator is used, at least one IRQ pin must be chosen, otherwise build error would happen.

```
#include "r irq rx pinset.h"
#ifndef R IRQ RX H
#error "Please check IRQ port assignments in Smart Configurator"
#endif
```

See Section 2.8, Configuration Overview for details on configuration options.

Control registers for input pins to be used for IRQ sources must be correctly set up before the IRQ module can communicate with them. The IRQ module does not provide any means to initialize the pin registers--that needs to be done externally prior to calling IRQ API functions. Typically this would be accomplished at system startup time as part of a general pin initialization routine.

There is no need to set up interrupt vectors for IRQs as this software takes care of that automatically based on the IRQs that have been enabled for use at build time through the configuration options.

The first step in using IRQs at run time is to call the R_IRQ_Open() function, passing the desired IRQ number and other required settings. On completion, the IRQ will be active and ready to respond to the specified transition or state of the input pin. On the occurrence of an IRQ event, the ISR will call the callback function that you provided as an argument in your R IRQ Open() call.

Two convenient commands are provided in the R IRQ Control() function to allow changing the interrupt trigger mode, and the priority level. This permits the interrupt event to be adjusted to adapt to current conditions as desired. Interrupts for the selected IRQ number are disabled briefly while the R IRQ Control() function is making the changes.

Other IRQ settings are only configured at the R IRQ Open(); these are the settings that are not expected to frequently change. If they need to be changed later during run-time, the R_IRQ_Close() function must be called so that R_IRQ_Open() can be called again with new settings.

Generally, most of the IRQ API functions will require a 'handle' argument. This is used to identify the IRQ number that is selected for the operation. A handle is obtained by first calling the R IRQ Open() function. You must provide the address of a location where you will store the handle to R IRQ Open(), and on completion the handle will be available for use. Thereafter, simply pass the provided handle value for that IRQ number to the other IRQ functions when calling them. In your application you will need to keep track of which handle belongs to a given IRQ, as each IRQ will be assigned its own handle.

1.3.1 Using FIT IRQ module in C++ project

For C++ project, add FIT IRQ module interface header file within extern "C"{}:

```
Extern "C"
{
    #include "r_smc_entry.h"
    #include "r_irq_rx_if.h"
}
```

1.4 API Overview

Table 1.1 lists the API functions included in this module.

Table 1.1 API Functions

Function	Description
R_IRQ_Open()	Initializes the associated registers required to prepare the specified IRQ for use, enables interrupts, and provides the handle for use with other API functions. Takes a callback function pointer for responding to interrupt events. This function must be called before calling any other API functions.
R_ IRQ_Close()	Disables the specified IRQ and its associated interrupt.
R_IRQ_Control()	Handles special hardware or software operations for the IRQ.
R_IRQ_ReadInput()	Reads the current level of the pin assigned to the specified IRQ.
R_IRQ_InterruptEnable()	Enables or disables the ICU interrupt for the specified IRQ.
R_IRQ_GetVersion()	Returns the driver version number.
R_IRQ_IRClear()	This function clears the IR flag for the specified IRQ.

1.5 Limitations

This driver is applicable only to IRQ type interrupts; i.e.: external input pin interrupts.

2. API Information

This FIT module has been confirmed to operate under the following conditions.

2.1 Hardware Requirements

The MCU used must support the following functions:

- IRQ
- One or more available GPIO input pins that are configurable as interrupt sources

2.2 Software Requirements

This driver is dependent upon the following FIT modules:

- Renesas Board Support Package (r_bsp) v5.20 or higher. It assumes that the related I/O ports have been correctly initialized elsewhere prior to calling this software's API functions.
- Use of the digital filtering features requires that the peripheral clock (PCLK) has been initialized by an external procedure prior to calling the APIs of this module.

2.3 Limitations

2.3.1 RAM Location Limitations

In FIT, if a value equivalent to NULL is set as the pointer argument of an API function, error might be returned due to parameter check. Therefore, do not pass a NULL equivalent value as pointer argument to an API function.

The NULL value is defined as 0 because of the library function specifications. Therefore, the above phenomenon would occur when the variable or function passed to the API function pointer argument is located at the start address of RAM (address 0x0). In this case, change the section settings or prepare a dummy variable at the top of the RAM so that the variable or function passed to the API function pointer argument is not located at address 0x0.

In the case of the CCRX project (e2 studio V7.5.0), the RAM start address is set as 0x4 to prevent the variable from being located at address 0x0. In the case of the GCC project (e2 studio V7.5.0) and IAR project (EWRX V4.12.1), the start address of RAM is 0x0, so the above measures are necessary. The default settings of the section may be changed due to the IDE version upgrade. Please check the section settings when using the latest IDE.

2.4 Supported Toolchain

This driver has been confirmed to work with the toolchain listed in 6.1, Confirmed Operation Environment.

2.5 Interrupt Vector

When a change of state on an IRQ input pin occurs that matches the trigger mode setting an interrupt request is generated. If interrupts are enabled, the interrupt ISR will execute which will call your assigned callback function. It is within the callback that you will place the code that you want to occur immediately in response to the ISR. Since callbacks are being processed within the context of the interrupt, and interrupts are disabled at this time, it is strongly recommended that your callback function complete as quickly as possible to avoid missing other interrupts that might occur in the system.

IRQ interrupt is enabled by executing the **R_IRQ_Open()** function.

Table 2.1 lists the interrupt vector used in the IRQ FIT Module.

Table 2.1 Interrupt Vector Used in the IRQ FIT Module

Device	Interrupt Vector	
RX110*1	IRQ0 interrupt (vector no.: 64)	
RX111*1	IRQ1 interrupt (vector no.: 65)	
RX113*1	IRQ2 interrupt (vector no.: 66)	
RX130*1	IRQ3 interrupt (vector no.: 67)	
RX13T*2	IRQ4 interrupt (vector no.: 68)	
RX140 *4	IRQ5 interrupt (vector no.: 69)	
RX230*1	IRQ6 interrupt (vector no.: 70)	
RX231*1	IRQ7 interrupt (vector no.: 71)	
RX23T*2	IRQ8 interrupt (vector no.: 72)	
RX23W*3	IRQ9 interrupt (vector no.: 73)	
RX23E-A*1	IRQ10 interrupt (vector no.: 74)	
RX23E-B*1	IRQ11 interrupt (vector no.: 75)	
RX24T*1	IRQ12 interrupt (vector no.: 76)	
RX24U *1	IRQ13 interrupt (vector no.: 77)	
RX26T	IRQ14 interrupt (vector no.: 78)	
RX260*1	IRQ15 interrupt (vector no.: 79)	
RX261*1		
RX64M		
RX651		
RX65N		
RX66T		
RX66N		
RX660		
RX671		
RX71M		
RX72T		
RX72M		
RX72N		

Note 1. Only have IRQ0 to IRQ7.

2.6 Header Files

All API calls and their supporting interface definitions are located in r irq rx if.h.

Note 2. Only have IRQ0 to IRQ5.

Note 3. Only have IRQ0, IRQ1, IRQ4 to IRQ7.

Note 4. Only have IRQ0 to IRQ2, IRQ4 to IRQ7.

2.7 Integer Types

This project uses ANSI C99. These types are defined in stdint.h.

2.8 Configuration Overview

The configuration option settings of this module are located in r_irq_rx_config.h. The option names and setting values are listed in the table below:

Configura	tion options in r_irq_rx_config.h
IRQ_CFG_REQUIRE_LOCK 1	If defined as 1 then the R_IRQ_Open() function will attempt to obtain a BSP lock for the duration of the function execution. This is to protect its internal state from reentrant access. On exit the lock will be released. This option may be set to 0 if BSP locking is not required or available in the system.
IRQ_CFG_PARAM_CHECKING	Checking of arguments passed to IRQ API functions can be enabled or disabled. Disabling argument checking is provided for systems that absolutely require faster and smaller code. By default the module is configured to use the setting of the systemwide BSP CFG PARAM CHECKING ENABLE macro. This can be
* Default = BSP_CFG_PARAM_ CHECKING_ENABLE	locally overridden for the IRQ module by redefining IRQ_CFG_PARAM_CHECKING. To control parameter checking locally, set IRQ_CFG_PARAM_CHECKING to 1 to enable it, otherwise set to 0 skip checking.
IRQ_PORT_IRQn_PORT IRQ_PORT_IRQn_BIT	The port and port-bit assignments to each IRQ must be defined so that the IRQ module can perform port specific operations, such as R_IRQ_ReadInput(). Set these as required according to the following format: #define IRQ_PORT_IRQ*_PORT ('m') (where m is the port number and the IRQ number replaces *) #define IRQ_PORT_IRQ*_BIT ('n') (where n is the bit number and the IRQ number replaces *) Note: Port assignments here must match the port configuration settings performed externally for them by the BSP
IRQ_CFG_FILT_EN_IRQn 0	If defined as 1 digital filtering is enabled for the IRQ number n. 0 = not enabled.
IRQ_CFG_FILT_PCLK_IRQn	PCLK digital filter clock divisor setting for the IRQ number n. Select from one of the predefined constants IRQ_CFG_PCLK_DIVxx. Example: /* Filter sample clock divisor for IRQ 0 = PCLK/64. */ #define IRQ_CFG_FILT_PLCK_IRQ0 (IRQ_CFG_PCLK_DIV64)
IRQ_CFG_NESTED_INT_EN_IRQn 0	If defined as 1 nested interrupt is enabled for the IRQ number n. 0 = not enabled.

2.9 Code Size

Typical code sizes associated with this module are listed below.

The ROM (code and constants) and RAM (global data) sizes are determined by the build-time configuration options described in 2.8, Configuration Overview. The table lists reference values when the C compiler's compile options are set to their default values, as described in 2.4, Supported Toolchains. The compile option default values are optimization level: 2, optimization type: for size, and data endianness: little-endian. The code size varies depending on the C compiler version and compile options.

	ROM, RAM and Stack Code Sizes							
			Memo	ory Used				
Device	Category		Renesas Compiler		Remarks			
Device	Oate	gory	With Parameter	Without Parameter	Remarks			
		Ī	Checking	Checking				
RX110,		1 IRQ	777 bytes	527 bytes				
RX111	ROM	8 IRQs	1377 bytes	1127 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)			
		1 IRQ	12 bytes	4 bytes				
	RAM	8 IRQs	40 bytes	32 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)			
	Maximum s	tack usage	48 bytes	46 bytes	The maximum value when one channel is used is listed.			
RX130,		1 IRQ	777 bytes	527 bytes				
RX230, RX24T, RX24U	ROM	8 IRQs	1366 bytes	1116 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)			
		1 IRQ	12 bytes	4 bytes				
	RAM	8 IRQs	40 bytes	32 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)			
	Maximum s	tack usage	48 bytes	36 bytes	The maximum value when one channel is used is listed.			

	ROM, RAM and Stack Code Sizes							
			Memo	ory Used				
Device	Category		Renesas Compiler		Remarks			
201100			With Parameter	Without Parameter	riomento			
			Checking	Checking				
RX23T		1 IRQ	767 bytes	521 bytes				
	ROM	6 IRQs	1207 bytes	961 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)			
		1 IRQ	10 bytes	4 bytes				
	RAM	6 IRQs	30 bytes	24 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)			
	Maximum	stack usage	48 bytes	36 bytes	The maximum value when one channel is used is listed.			
	ROM	1 IRQ	696 bytes	448 bytes				
		6 IRQs	986 bytes	738 bytes	ROM size is the sum of Program, Constant, and Initialized data.			
		1 IRQ	12 bytes	4 bytes				
RX23W	RAM	6 IRQs	32 bytes	24 bytes	RAM size is the sum of Uninitialized data, Data, Stack and Others.			
	Maximum stack usage		84 bytes	76 bytes	Maximum stack usage is the sum of the maximum size of peripheral API and maximum stack size of peripheral interrupt.			
RX64M,		1 IRQ	892 bytes	640 bytes				
RX65N, RX66T, RX71M	ROM	16 IRQs	2180 bytes	1928 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)			
		1 IRQ	20 bytes	4 bytes				
	RAM	16 IRQs	80 bytes	64 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)			
	Maximum	stack usage	48 bytes	40 bytes	The maximum value when one channel is used is listed.			

	ROM, RAM and Stack Code Sizes							
			Memo	ory Used				
Device	Category			s Compiler	Remarks			
2011.00			With Parameter Checking	Without Parameter Checking				
RX113,		1 IRQ	777 bytes	529 bytes				
RX231	ROM	8 IRQs	1366 bytes	1118 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)			
		1 IRQ	12 bytes	4 bytes				
	RAM	8 IRQs	40 bytes	32 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)			
	Maximum s	tack usage	48 bytes	36 bytes	The maximum value when one channel is used is listed.			
RX72T		1 IRQ	892 bytes	640 bytes				
	ROM	16 IRQs	2181 bytes	1929 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)			
		1 IRQ	20 bytes	4 bytes				
	RAM	16 IRQs	80 bytes	64 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)			
	Maximum s	tack usage	48 bytes	40 bytes	The maximum value when one channel is used is listed.			
		1 IRQ	879 bytes	620 bytes				
	ROM	16 IRQs	2160 bytes	1901 bytes	ROM size is the sum of Program, Constant, and Initialized data.			
		1 IRQ	20 bytes	4 bytes				
RX72M	RAM	16 IRQs	80 bytes	64 bytes	RAM size is the sum of Uninitialized data, Data, Stack and Others.			
	Maximum stack usage		84 bytes	80 bytes	Maximum stack usage is the sum of the maximum size of peripheral API and maximum stack size of peripheral interrupt.			

	ROM, RAM and Stack Code Sizes							
				ory Used				
Device	Category		Renesas Compiler		Remarks			
			With Parameter Checking	Without Parameter Checking				
RX13T	1 IRQ		695 bytes	440 bytes				
KX131	ROM	6 IRQs	985 bytes	730 bytes	ROM size is the sum of Program, Constant, and Initialized data.			
		1 IRQ	10 bytes	4 bytes				
	RAM	6 IRQs	30 bytes	24 bytes	RAM size is the sum of Uninitialized data, Data, Stack and Others.			
	Maximum stack usage		84 bytes	80 bytes	Maximum stack usage is the sum of the maximum size of peripheral API and maximum usage stack size of interrupts functions.			
RX66N		1 IRQ	819 bytes	560 bytes				
	ROM	16 IRQs	2100 bytes	1841 bytes	ROM size is the sum of Program, Constant, and Initialized data.			
		1 IRQ	20 bytes	4 bytes				
	RAM	16 IRQs	80 bytes	64 bytes	RAM size is the sum of Uninitialized data, Data, Stack and Others.			
	Maximum stack usage		72 bytes	72 bytes	Maximum stack usage is the sum of the maximum size of peripheral API and maximum usage stack size of interrupts functions.			
RX72N		1 IRQ	819 bytes	560 bytes				
	ROM	6 IRQs	2100 bytes	1841 bytes	ROM size is the sum of Program, Constant, and Initialized data.			
		1 IRQ	20 bytes	4 bytes				
	RAM	6 IRQs	80 bytes	64 bytes	RAM size is the sum of Uninitialized data, Data, Stack and Others.			
	Maximum stack usage		72 bytes	72 bytes	Maximum stack usage is the sum of the maximum size of peripheral API and maximum usage stack size of interrupts functions.			

	ROM, RAM and Stack Code Sizes							
			Memo	ory Used				
Device	Category		Renesas Compiler		Remarks			
Device			With Parameter	Without Parameter	Remarks			
			Checking	Checking				
		1 IRQ	786 bytes	531 bytes				
	ROM	8 IRQs	1385 bytes	1130 bytes	ROM size is the sum of Program, Constant, and Initialized data.			
		1 IRQ	12 bytes	4 bytes				
RX23E- A	RAM	8 IRQs	40 bytes	32 bytes	RAM size is the sum of Uninitialized data, Data, Stack and Others.			
	Maximum s	stack usage	76 bytes	76 bytes	Maximum stack usage is the sum of the maximum size of peripheral API and maximum stack size of peripheral interrupt.			
	ROM	1 IRQ	871 bytes	599 bytes				
		16 IRQs	2141 bytes	1869 bytes	ROM size is the sum of Program, Constant, and Initialized data.			
	RAM	1 IRQ	20 bytes	4 bytes				
RX671		16 IRQs	80 bytes	64 bytes	RAM size is the sum of Uninitialized data, Data, Stack and Others.			
	Maximum stack usage		72 bytes	68 bytes	Maximum stack usage is the sum of the maximum size of peripheral API and maximum stack size of peripheral interrupt.			
	ROM	1 IRQ	855 bytes	571 bytes				
		8 IRQs	1362 bytes	1078 bytes	ROM size is the sum of Program, Constant, and Initialized data.			
	RAM	1 IRQ	12 bytes	4 bytes				
RX140		8 IRQs	36 bytes	28 bytes	RAM size is the sum of Uninitialized data, Data, Stack and Others.			
	Maximum stack usage		72 bytes	64 bytes	Maximum stack usage is the sum of the maximum size of peripheral API and maximum stack size of peripheral interrupt.			
	ROM	1 IRQ	962 bytes	677 bytes				
		16 IRQs	2257 bytes	1972 bytes	ROM size is the sum of Program, Constant, and Initialized data.			
	RAM	1 IRQ	20 bytes	4 bytes				
RX660		16 IRQs	80 bytes	64 bytes	RAM size is the sum of Uninitialized data, Data, Stack and Others.			
	Maximum stack usage		72 bytes	68 bytes	Maximum stack usage is the sum of the maximum size of peripheral API and maximum stack size of peripheral interrupt.			

	ROM, RAM and Stack Code Sizes							
			Memo	ory Used				
Device	Car	togony	Renesas Compiler		Remarks			
Device	Category		With Parameter Checking	Without Parameter Checking	Remains			
	ROM	1 IRQ	980 bytes	695 bytes				
		16 IRQs	2552 bytes	2267 bytes	ROM size is the sum of Program, Constant, and Initialized data.			
	RAM	1 IRQ	20 bytes	4 bytes				
RX26T		16 IRQs	80 bytes	64 bytes	RAM size is the sum of Uninitialized data, Data, Stack and Others.			
	Maximum	stack usage	84 bytes	84 bytes	Maximum stack usage is the sum of the maximum size of peripheral API and maximum stack size of peripheral interrupt.			
	ROM	1 IRQ	850 bytes	571 bytes				
		8 IRQs	1444 bytes	1165 bytes	ROM size is the sum of Program, Constant, and Initialized data.			
RX23E-	RAM	1 IRQ	12 bytes	4 bytes				
B		8 IRQs	40 bytes	32 bytes	RAM size is the sum of Uninitialized data, Data, Stack and Others.			
	Maximum stack usage		72 bytes	64 bytes	Maximum stack usage is the sum of the maximum size of peripheral API and maximum stack size of peripheral interrupt.			
	ROM	1 IRQ	850 bytes	571 bytes				
		8 IRQs	1439 bytes	1160 bytes	ROM size is the sum of Program, Constant, and Initialized data.			
	RAM	1 IRQ	12 bytes	4 bytes				
RX260		8 IRQs	40 bytes	32 bytes	RAM size is the sum of Uninitialized data, Data, Stack and Others.			
	Maximum stack usage		72 bytes	64 bytes	Maximum stack usage is the sum of the maximum size of peripheral API and maximum stack size of peripheral interrupt.			
	ROM	1 IRQ	850 bytes	571 bytes				
		8 IRQs	1439 bytes	1160 bytes	ROM size is the sum of Program, Constant, and Initialized data.			
RX261	RAM	1 IRQ	12 bytes	4 bytes				
100201		8 IRQs	40 bytes	32 bytes	RAM size is the sum of Uninitialized data, Data, Stack and Others.			
	Maximum stack usage		72 bytes	64 bytes	Maximum stack usage is the sum of the maximum size of peripheral API and maximum stack size of peripheral interrupt.			

			ROM, RAM and	Stack Code Sizes	
				ory Used	
Device	Category -		With Parameter Checking	CC Without Parameter Checking	Remarks
RX110,		1 IRQ	1532 bytes	1140 bytes	
RX111	ROM	8 IRQs	2592 bytes	2200 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)
		1 IRQ	12 bytes	4 bytes	
	RAM	8 IRQs	40 bytes	32 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)
	Maximum stack usage		-	-	The maximum value when one channel is used is listed.
RX130,	ROM	1 IRQ	1532 bytes	1140 bytes	
RX230, RX24T, RX24U		8 IRQs	2592 bytes	2200 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)
		1 IRQ	12 bytes	4 bytes	
	RAM	8 IRQs	40 bytes	32 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)
	Maximum stack usage		-	-	The maximum value when one channel is used is listed.
		1 IRQ	1604 bytes	1204 bytes	
	ROM	6 IRQs	2360 bytes	1960 bytes	ROM size is the sum of Program, Constant, and Initialized data.
RX13T		1 IRQ	12 bytes	4 bytes	
100101	RAM	6 IRQs	32 bytes	24 bytes	RAM size is the sum of Uninitialized data, Data, Stack and Others.
	Maximum stack usage		-	-	The maximum value when one channel is used is listed.

			ROM, RAM and	Stack Code Sizes	
				ory Used	
Device	Category -		With Parameter Checking	GCC Without Parameter Checking	Remarks
RX23T		1 IRQ	1532 bytes	1140 bytes	
	ROM	6 IRQs	4048 bytes	3656 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)
		1 IRQ	20 bytes	4 bytes	
	RAM	6 IRQs	80 bytes	64 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)
	Maximum s	tack usage	-	-	The maximum value when one channel is used is listed.
RX64M,		1 IRQ	1772 bytes	1380 bytes	
RX65N, RX66T, RX71M	ROM	16 IRQs	2288 bytes	1904 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)
		1 IRQ	8 bytes	4 bytes	
	RAM	16 IRQs	28 bytes	24 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)
	Maximum s	tack usage	-	-	The maximum value when one channel is used is listed.
RX66N		1 IRQ	596 bytes	164 bytes	
	ROM	16 IRQs	2872 bytes	2440 bytes	ROM size is the sum of Program, Constant, and Initialized data.
		1 IRQ	20 bytes	4 bytes	
	RAM	16 IRQs	80 bytes	64 bytes	RAM size is the sum of Uninitialized data, Data, Stack and Others.
	Maximum s	tack usage	-	-	The maximum value when one channel is used is listed.

			ROM, RAM and	Stack Code Sizes	
	Category -			ory Used	
Device			With Parameter Checking	GCC Without Parameter Checking	Remarks
RX113,		1 IRQ	1540 bytes	1148 bytes	
RX231	ROM	8 IRQs	2600 bytes	2216 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)
		1 IRQ	12 bytes	4 bytes	
	RAM	8 IRQs	40 bytes	32 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)
	Maximum stack usage		-	-	The maximum value when one channel is used is listed.
RX72T		1 IRQ	1772 bytes	1380 bytes	
	ROM	16 IRQs	4048 bytes	3656 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)
		1 IRQ	20 bytes	4 bytes	
	RAM	16 IRQs	80 bytes	64 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)
	Maximum s	tack usage	-	-	The maximum value when one channel is used is listed.
		1 IRQ	1892 bytes	1484 bytes	
	ROM	16 IRQs	4168 bytes	3760 bytes	ROM size is the sum of Program, Constant, and Initialized data.
RX72M		1 IRQ	20 bytes	4 bytes	
IXA ZIVI	RAM	16 IRQs	80 bytes	64 bytes	RAM size is the sum of Uninitialized data, Data, Stack and Others.
	Maximum s	tack usage	-	-	The maximum value when one channel is used is listed.

	ROM, RAM and Stack Code Sizes						
				ory Used			
Device	Category -		With Parameter Checking	GCC Without Parameter Checking	Remarks		
		1 IRQ	596 bytes	164 bytes			
	ROM	16 IRQs	2872 bytes	2440 bytes	ROM size is the sum of Program, Constant, and Initialized data.		
RX72N		1 IRQ	20 bytes	4 bytes			
TOAT ZIN	RAM	16 IRQs	80 bytes	64 bytes	RAM size is the sum of Uninitialized data, Data, Stack and Others.		
	Maximum s	tack usage	-	-	The maximum value when one channel is used is listed.		
		1 IRQ	1652 bytes	1236 bytes			
	ROM	8 IRQs	2704 bytes	2296 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)		
RX23E-		1 IRQ	12 bytes	4 bytes			
A	RAM	8 IRQs	40 bytes	32 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)		
	Maximum stack usage.		-	-	The maximum value when one channel is used is listed.		
		1 IRQ	1912 bytes	1480 bytes			
	ROM	16 IRQs	4172 bytes	3748 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)		
DY671		1 IRQ	20 bytes	4 bytes			
RX671	RAM	16 IRQs	80 bytes	64 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)		
	Maximum s	tack usage.	-	-	The maximum value when one channel is used is listed.		

			ROM, RAM and	Stack Code Sizes	
	Category			ory Used	
Device			G	CC	Remarks
		.g,	With Parameter	Without Parameter	
		1	Checking	Checking	
	ROM	1 IRQ	1784 bytes	1328 bytes	
		8 IRQs	2836 bytes	2388 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)
RX140	RAM	1 IRQ	12 bytes	4 bytes	
10(140		8 IRQs	40 bytes	32 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)
	Maximum s	stack usage.	-	-	The maximum value when one channel is used is listed.
		1 IRQ	2056 bytes	1600 bytes	
	ROM	16 IRQs	4316 bytes	3856 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)
RX660	RAM	1 IRQ	0 bytes	0 bytes	
KA000		16 IRQs	128 bytes	128 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)
	Maximum stack usage.		-	-	The maximum value when one channel is used is listed.
		1 IRQ	1204 bytes	860 bytes	
	ROM	16 IRQs	2528 bytes	2176 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)
RX26T		1 IRQ	0 bytes	0 bytes	
10,201	RAM	16 IRQs	128 bytes	128 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)
	Maximum s	stack usage.	-	-	The maximum value when one channel is used is listed.

			ROM, RAM and	Stack Code Sizes	
				ry Used	
Device	Cate	egory		CC	Remarks
			With Parameter	Without Parameter	
		1 IRQ	Checking	Checking 684 bytes	
		TING	1036 bytes 1632 bytes	1280 bytes	ROM size can be calculated with
	ROM	8 IRQs	1002 37,00	1230 57.00	the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)
RX23E-		1 IRQ	12 bytes	4 bytes	
В	RAM	8 IRQs	40 bytes	32 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)
	Maximum	stack usage.	-	-	The maximum value when one channel is used is listed.
		1 IRQ	1036 bytes	692 bytes	
	ROM	8 IRQs	1640 bytes	1296 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)
RX260	RAM	1 IRQ	12 bytes	4 bytes	
RAZ00		8 IRQs	40 bytes	32 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)
	Maximum stack usage.		-	-	The maximum value when one channel is used is listed.
		1 IRQ	1028 bytes	684 bytes	
	ROM	8 IRQs	1640 bytes	1288 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)
RX261		1 IRQ	12 bytes	4 bytes	
KAZ01	RAM	8 IRQs	40 bytes	32 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)
	Maximum	stack usage.	-	-	The maximum value when one channel is used is listed.

	ROM, RAM and Stack Code Sizes							
				ry Used				
Device	Cate	orv	IAR Compiler		Remarks			
		, ,	With Parameter Checking	Without Parameter Checking				
RX110,		1 IRQ	1120 bytes	792 bytes				
RX111	ROM	8 IRQs	1676 bytes	1348 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)			
		1 IRQ	12 bytes	4 bytes				
	RAM	8 IRQs	40 bytes	32 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)			
	Maximum sta		152 bytes	152 bytes	The maximum value when one channel is used is listed.			
RX130,		1 IRQ	1120 bytes	792 bytes				
RX230, RX24T, RX24U	ROM	8 IRQs	1672 bytes	1344 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)			
		1 IRQ	12 bytes	4 bytes				
	RAM	8 IRQs	40 bytes	32 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)			
	Maximum stack usage		152 bytes	152 bytes	The maximum value when one channel is used is listed.			
	ROM	1 IRQ	1112 bytes	784 bytes				
		6 IRQs	1509 bytes	1184 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)			
RX13T	RAM	1 IRQ	12 bytes	4 bytes				
100101		6 IRQs	32 bytes	24 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)			
	Maximum st	ack usage	104 bytes	104 bytes	The maximum value when one channel is used is listed.			

	ROM, RAM and Stack Code Sizes							
	H		Memo	ry Used				
Device	evice Cate	orv	IAR Compiler		Remarks			
2011.00	53.15	,	With Parameter Checking	Without Parameter Checking				
RX23T		1 IRQ	1112 bytes	784 bytes				
	ROM	6 IRQs	1504 bytes	1176 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)			
		1 IRQ	8 bytes	4 bytes				
	RAM	6 IRQs	28 bytes	24 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)			
	Maximum stack usage		152 bytes	152 bytes	The maximum value when one channel is used is listed.			
RX64M,		1 IRQ	1338 bytes	1039 bytes				
RX65N, RX66T, RX71M	ROM	16 IRQs	2523 bytes	2289 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)			
		1 IRQ	20 bytes	4 bytes				
	RAM	16 IRQs	80 bytes	64 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)			
	Maximum st	tack usage	168 bytes	168 bytes	The maximum value when one channel is used is listed.			
RX66N		1 IRQ	1278 bytes	937 bytes				
	ROM	16 IRQs	2463 bytes	2128 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)			
		1 IRQ	20 bytes	4 bytes				
	RAM	16 IRQs	80 bytes	64 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)			
	Maximum st	tack usage	88 bytes	88 bytes	The maximum value when one channel is used is listed.			

			ROM, RAM an	d Stack Code Sizes	
	<u>.</u>		Memo	ry Used	
Device	Cate	norv	IAR Compiler		Remarks
Device	Cate	gory	With Parameter	Without Parameter	Remarks
		T	Checking	Checking	
RX113,		1 IRQ	1120 bytes	792 bytes	
RX231	ROM	8 IRQs	1674 bytes	1346 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)
		1 IRQ	12 bytes	4 bytes	
	RAM	8 IRQs	40 bytes	32 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)
	Maximum sta		152 bytes	152 bytes	The maximum value when one channel is used is listed.
RX72T		1 IRQ	1319 bytes	984 bytes	
	ROM	16 IRQs	2504 bytes	2167 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)
		1 IRQ	20 bytes	4 bytes	
	RAM	16 IRQs	80 bytes	64 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)
	Maximum s	tack usage	168 bytes	168 bytes	The maximum value when one channel is used is listed.
		1 IRQ	1320 bytes	992 bytes	
	ROM	16 IRQs	2505 bytes	2174 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)
RX72M		1 IRQ	20 bytes	4 bytes	
RA/ZIVI	RAM	16 IRQs	80 bytes	64 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)
	Maximum s	tack usage	172 bytes	172 bytes	The maximum value when one channel is used is listed.

ROM, RAM and Stack Code Sizes							
				ry Used			
Device	Cate	orv	IAR Compiler		Remarks		
2000	J,	,	With Parameter Checking	Without Parameter Checking			
		1 IRQ	1278 bytes	937 bytes			
	ROM	16 IRQs	2463 bytes	2128 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)		
RX72N		1 IRQ	20 bytes	4 bytes			
KA/ZIN	RAM	16 IRQs	80 bytes	64 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)		
	Maximum st	tack usage	88 bytes	88 bytes	The maximum value when one channel is used is listed.		
		1 IRQ	1054 bytes	718 bytes			
	ROM	8 IRQs	1606 bytes	1272 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)		
RX23E-		1 IRQ	12 bytes	4 bytes	·		
A	RAM	8 IRQs	40 bytes	32 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)		
	Maximum st	tack usage	76 bytes	76 bytes	The maximum value when one channel is used is listed.		
		1 IRQ	1301 bytes	969 bytes			
	ROM	16 IRQs	2486 bytes	2155 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)		
RX671		1 IRQ	20 bytes	4 bytes			
100/1	RAM	16 IRQs	80 bytes	64 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)		
	Maximum st	tack usage	76 bytes	76 bytes	The maximum value when one channel is used is listed.		

ROM, RAM and Stack Code Sizes							
			Memo	ry Used			
Device	Category		IAR Compiler		Remarks		
Device	Cale	gory	With Parameter	Without Parameter	Remarks		
		1	Checking	Checking			
		1 IRQ	1168 bytes	801 bytes			
	ROM	16 IRQs	1646 bytes	1279 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)		
RX140		1 IRQ	12 bytes	4 bytes			
KX140	RAM	16 IRQs	36 bytes	28 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)		
	Maximum s	tack usage	76 bytes	76 bytes	The maximum value when one channel is used is listed.		
		1 IRQ	1431 bytes	1056 bytes			
	ROM	16 IRQs	2616 bytes	2239 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)		
D\(000	RAM	1 IRQ	20 bytes	4 bytes	,		
RX660		16 IRQs	80 bytes	64 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)		
	Maximum stack usage		76 bytes	76 bytes	The maximum value when one channel is used is listed.		
		1 IRQ	1424 bytes	1056 bytes			
	ROM	16 IRQs	2609 bytes	2240 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)		
RX26T		1 IRQ	20 bytes	4 bytes			
KAZ01	RAM	16 IRQs	80 bytes	64 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)		
	Maximum s	tack usage	76 bytes	76 bytes	The maximum value when one channel is used is listed.		

	ROM, RAM and Stack Code Sizes							
			Memo	ry Used				
Device	Cate	norv	IAR Compiler		Remarks			
Bevice	Category		With Parameter Checking	Without Parameter Checking	Remarks			
		1 IRQ	1229 bytes	864 bytes				
	ROM	8 IRQs	1782 bytes	1415 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)			
RX23E-		1 IRQ	12 bytes	4 bytes				
В	RAM	8 IRQs	40 bytes	32 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)			
	Maximum s	tack usage	76 bytes	76 bytes	The maximum value when one channel is used is listed.			
		1 IRQ	1239 bytes	872 bytes				
	ROM	8 IRQs	1792 bytes	1064 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)			
RX260	RAM	1 IRQ	12 bytes	4 bytes				
KA200		8 IRQs	40 bytes	12 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)			
	Maximum stack usage		40 bytes	40 bytes	The maximum value when one channel is used is listed.			
		1 IRQ	1239 bytes	872 bytes				
	ROM	8 IRQs	1792 bytes	1424 bytes	ROM size can be calculated with the following formula: ROM size for 1 channel + (58 bytes x number of additional channels)			
RX261		1 IRQ	12 bytes	4 bytes				
100201	RAM	8 IRQs	40 bytes	32 bytes	RAM size can be calculated with the following formula: RAM size for 1 channel + (4 bytes x number of additional channels)			
	Maximum s	tack usage	40 bytes	40 bytes	The maximum value when one channel is used is listed.			

2.10 Parameters

This section describes the parameter structure used by the API functions in this module. The structure is located in r_irq_rx_if.h as are the prototype declarations of API functions.

2.10.1 Special Data Types

To provide strong type checking and reduce errors, many parameters used in API functions require arguments to be passed using the provided type definitions. Allowable values are defined in the public interface file *r_irq_rx_if.h*. The following special types have been defined:

Enumeration of IRQ numbers

Type: irq_number_t **Macro:** IRQ_NUM_n

Values (n): (all MCUs) 0 through 7 (and for RX MCUs with 16 IRQs) 8 through 15

Example: IRQ_NUM_2

IRQ control command codes

Type: irq_cmd_t

Values: IRQ_CMD_SET_PRIO, IRQ_CMD_SET_TRIG

IRQ interrupt priority settings.

Type: irq_prio_t

Macro: IRQ_PRI_n

Value s (n): 0 through 15 Example: IRQ_PRI_3

IRQ trigger mode settings

Type: irq_trigger_t

 $\begin{tabular}{ll} \textbf{Values:} & IRQ_TRIG_LOWLEV, & IRQ_TRIG_FALLING, & IRQ_TRIG_RISING, \\ IRQ & TRIG & BOTH & EDGE \\ \end{tabular}$

Handle

Type: irq_handle_t

Values: User provides pointer to storage for this type for a handle. Handle value is automatically

assigned by R_IRQ_Open function

2.11 Return Values

This section describes return values of API functions. This enumeration is located in r_irq_rx_if.h as are the prototype declarations of API functions.

Return Type: irq_err_t

Values:	Cause
IRQ_SUCCESS	Function completed without errors
IRQ_ERR_BAD_NUM	Invalid IRQ number was passed
IRQ_ERR_NOT_OPENED	IRQ not yet opened. Function cannot be completed.
IRQ_ERR_NOT_CLOSED	IRQ still open from previous open.
IRQ_ERR_UNKNOWN_CMD	Control command is not recognized.
IRQ_ERR_INVALID_ARG	Argument is not valid for parameter.
IRQ_ERR_INVALID_PTR	Received null pointer; missing required argument.
IRQ_ERR_LOCK	A lock procedure failed.

2.12 Callback Function

In this module, the callback function specified by the user is called when the IRQ interrupt occurs.

The callback function is specified by storing the address of the user function in the "void (*const pcallback)(void *pargs))" structure member (see 2.10, Parameters). When the callback function is called, the variable which stores the channel number is passed as the argument.

The argument is passed as void type. Thus, the argument of the callback function is cast to a void pointer. See examples below as reference.

When using a value in the callback function, type cast the value.

```
void my_irq_callback(void * pdata)
{
    irq_number_t my_triggered_irq_number;

    my_triggered_irq_number = *((irq_number_t *)pdata);
    ...
}
```

2.13 Adding the FIT Module to Your Project

This module must be added to each project in which it is used. Renesas recommends the method using the Smart Configurator described in (1) or (2) below. However, the Smart Configurator only supports some RX devices. Please use the methods of (3) for RX devices that are not supported by the Smart Configurator.

- (1) Adding the FIT module to your project using the Smart Configurator in e² studio
 By using the Smart Configurator in e² studio, the FIT module is automatically added to your project.
 Refer to "Renesas e² studio Smart Configurator User Guide (R20AN0451)" for details.
- (2) Adding the FIT module to your project using the Smart Configurator in CS+ By using the Smart Configurator Standalone version in CS+, the FIT module is automatically added to your project. Refer to "Renesas e² studio Smart Configurator User Guide (R20AN0451)" for details.
- (3) Adding the FIT module to your project in CS+ In CS+, please manually add the FIT module to your project. Refer to "Adding Firmware Integration Technology Modules to CS+ Projects (R01AN1826)" for details.

2.14 "for", "while" and "do while" statements

In this module, "for", "while" and "do while" statements (loop processing) are used in processing to wait for register to be reflected and so on. For these loop processing, comments with "WAIT_LOOP" as a keyword are described. Therefore, if user incorporates fail-safe processing into loop processing, user can search the corresponding processing with "WAIT_LOOP".

The following shows example of description.

```
while statement example :

/* WAIT_LOOP */
while(0 == SYSTEM.OSCOVFSR.BIT.PLOVF)
{

/* The delay period needed is to make sure that the PLL has stabilized. */
}

for statement example :

/* Initialize reference counters to 0. */

/* WAIT_LOOP */
for (i = 0; i < BSP_REG_PROTECT_TOTAL_ITEMS; i++)
{

g_protect_counters[i] = 0;
}

do while statement example :

/* Reset completion waiting */
do

{

reg = phy_read(ether_channel, PHY_REG_CONTROL);
count++;
} while ((freg & PHY_CONTROL_RESET) && (count < ETHER_CFG_PHY_DELAY_RESET)); /* WAIT_LOOP */
```

3. API Functions

R_IRQ_Open()

This function initializes the associated IRQ registers, enables interrupts, and provides the handle for use with other API functions. This function must be called before calling any other API functions.

Format

Parameters

```
irq_number_t irq_number
```

Number of the IRQ to be initialized.

irq_trigger_t trigger

Enumerated type for trigger type: low level, rising edge, falling edge, both edges.

irg prio t priority

Enumerated priority level setting for the IRQ.

irq handle t phandle

Pointer to a location for handle for IRQ. Handle value will be set by this function.

pcallback

Pointer to function called from interrupt.

Return Values

```
[IRQ_SUCCESS]
                             /* Successful; IRQ initialized
[IRQ_ERR_BAD_NUM]
                                                                                         */
                             /* IRQ number is invalid or unavailable
                                                                                         */
[IRQ ERR NOT CLOSED]
                             /* IRQ currently in operation: Perform R IRQ Close() first
                                                                                         */
[IRQ ERR INVALID PTR]
                             /* phandle pointer is NULL
                                                                                         */
                             /* An invalid argument value was passed.
[IRQ ERR INVALID ARG]
IIRQ ERR LOCK
                             /* The lock could not be acquired.
```

Properties

Prototyped in file "r_irq_rx_if.h".

Description

The Open function is responsible for preparing an IRQ for operation. After completion of the Open function the IRQ shall be enabled and ready to service interrupts. This function must be called once prior to calling any other IRQ API functions. Once successfully completed, the status of the selected IRQ will be set to "open". After that this function should not be called again for the same IRQ without first performing a "close" by calling R_IRQ_Close().

Example

Special Notes:

None.

R_IRQ_Control()

The Control function is responsible for handling special hardware or software operations for the IRQ.

Format

Parameters

irq_cmd_t cmd

Enumerated command codes:

```
IRQ_CMD_SET_PRIO - Changes the interrupt priority level.
IRQ_CMD_SET_TRIG - Changes the interrupt triggering mode.
```

pcmd_data

Pointer to the command-data structure parameter of type void that is used to reference the location of any data specific to the command that is needed for its completion.

Return Values

```
[IRQ_SUCCESS] /* Command successfully completed. */
[IRQ_ERR_NOT_OPENED] /* The IRQ has not been opened. Perform R_IRQ_Open() first */
[IRQ_ERR_BAD_NUM] /* IRQ number is invalid or unavailable */
[IRQ_ERR_UNKNOWN_CMD] /* Control command is not recognized. */
[IRQ_ERR_INVALID_PTR] /* pcmd_data pointer or handle is NULL */
[IRQ_ERR_INVALID_ARG] /* An element of the pcmd_data structure contains an invalid value. */
[IRQ_ERR_LOCK] /* The lock could not be acquired */
```

Properties

Prototyped in file "r_irq_rx_if.h"

Description

This function is responsible for handling special hardware or software operations for the IRQ. It takes an IRQ handle to identify the selected IRQ, an enumerated command value to select the operation to be performed, and a void pointer to a location that contains information or data required to complete the operation. This pointer must point to storage that has been type-cast by the caller for the particular command using the appropriate type provided in "r_irq_rx_if.h".

Example

```
/* Change trigger mode to rising edge. */
irq_trigger_t     my_trig_mode = IRQ_TRIG_RISING;

result = R_IRQ_Control(my_handle, IRQ_CMD_SET_TRIG, &my_trig_mode);

/* Change the priority. */
irq_prio_t my_priority = IRQ_PRI_10;

result = R_IRQ_Control(my_handle, IRQ_CMD_SET_PRIO, &my_priority);
```

Special Notes:

None.

R_IRQ_Close()

Fully disables the IRQ designated by the handle.

Format

Parameters

irq_handle_t handle
Handle for the IRQ.

Return Values

```
[IRQ_SUCCESS] /* Successful; IRQ closed */
[IRQ_ERR_NOT_OPENED] /* The IRQ has not been opened so closing has no effect. */
[IRQ_ERR_BAD_NUM] /* IRQ number is invalid or unavailable */
[IRQ_ERR_INVALID_PTR] /* A required pointer argument is NULL */
```

Properties

Prototyped in file "r_irq_rx_if.h"

Description

This function frees the IRQ by clearing its assignment to a port, and disables the associated interrupts. The IRQ handle is modified to indicate that it is no longer in the 'open' state. The IRQ cannot be used again until it has been reopened with the R_IRQ_Open function. If this function is called for an IRQ that is not in the open state then an error code is returned.

Example

```
irq_err_t result;
result = R_IRQ_Close(my_handle);
```

Special Notes:

None.

R_IRQ_ReadInput()

This function reads the current level of the pin assigned to the specified IRQ.

Format

Parameters

```
irq_handle_t const handle
Handle for the IRQ.
```

uint8_t plevel

Pointer to location where the input pin state can be returned.

Return Values

```
[IRQ_SUCCESS] /* Operation successfully completed. */
[IRQ_ERR_NOT_OPENED] /* The IRQ has not been opened. Perform R_IRQ_Open() first */
[IRQ_ERR_BAD_NUM] /* IRQ number is invalid or unavailable */
[IRQ_ERR_INVALID_PTR] /* plevel data pointer or handle is NULL */
```

Properties

Prototyped in file "r_irq_rx_if.h"

Description

This function reads the current level of the pin assigned to the specified IRQ. This is a realtime read which may indicate a different value than the level that initially triggered an interrupt. One example use is for cases in which a switch has triggered an interrupt and then needs to be polled for debounce.

Example

```
/* What logic level does the input currently see? */
uint8_t irq_pin_level;
result = R_IRQ_ReadInput(my_handle, (uint8_t*)&irq_pin_level);
```

Special Notes:

None.

R_IRQ_InterruptEnable()

This function enables or disables the ICU interrupt for the specified IRQ.

Format

Parameters

```
irq_handle_t const handle
Handle for the IRQ.

bool enable
true = enable the interrupt.
false = disable interrupt.
```

Return Values

```
[IRQ_SUCCESS] /* Operation successfully completed. */
[IRQ_ERR_NOT_OPENED] /* The IRQ has not been opened. Perform R_IRQ_Open() first */
[IRQ_ERR_BAD_NUM] /* IRQ number is invalid or unavailable */
[IRQ_ERR_INVALID_PTR] /* handle is NULL */
```

Properties

Prototyped in file "r_irq_rx_if.h"

Description

The function enables or disables the ICU interrupt for the IRQ specified by the handle argument. This function is potentially called frequently and is expected to execute quickly.

Example

```
irq_err_t result;
/* Enable interrupt */
result = R_IRQ_InterruptEnable (my_handle, true);
/* Disable interrupt */
result = R_IRQ_InterruptEnable (my_handle, false);
```

Special Notes:

None.

R_IRQ_GetVersion()

This function returns the driver version number at runtime.

Format

uint32_t R_IRQ_GetVersion (void)

Parameters

None.

Return Values

Version number with major and minor version digits packed into a single 32-bit value.

Properties

Prototyped in file "r irq rx if.h".

Description

The function returns the version of this module. The version number is encoded such that the top 2 bytes are the major version number and the bottom 2 bytes are the minor version number.

Example

```
/* Retrieve the version number and convert it to a string. */
uint32_t version, version_high, version_low;
char version_str[9];

version = R_IRQ_GetVersion();

version_high = (version >> 16) &0xf;
version_low = version & 0xff;

sprintf(version_str, "IRQv%1.1hu.%2.2hu", version_high, version_low);
```

Special Notes:

None.

R_IRQ_IRClear()

This function clears the IR flag for the specified IRQ.

Format

Parameters

irq_handle_t const handle Handle for the IRQ.

Return Values

```
[IRQ_SUCCESS] /* Operation successfully completed. */
[IRQ_ERR_NOT_OPENED] /* The IRQ has not been opened. Perform R_IRQ_Open() first */
[IRQ_ERR_BAD_NUM] /* IRQ number is invalid or unavailable */
[IRQ_ERR_INVALID_PTR] /* handle is NULL */
```

Properties

Prototyped in file "r_irq_rx_if.h"

Description

The function clears the IR flag for the IRQ specified by the handle argument.

Example

```
/* Clear IR flag */
irq_err_t result;
result = R_IRQ_IRClear (my_handle);
```

Special Notes:

The IR flag is cleared only when edge detection is used.

When the interrupt request destination is the DTC or DMAC, do not write 0 to the IR flag.

4. Pin Setting

To use the IRQ FIT module, assign input/output signals of the peripheral function to pins with the multi-function pin controller (MPC). The pin assignment is referred to as the "Pin Setting" in this document. Please perform the pin setting after calling the R_IRQ_Open() function.

When performing the Pin Setting in the e2 studio, the Pin Setting feature of the Smart Configurator can be used. When using the Pin Setting feature, a source file is generated according to the option selected in the Pin Setting window in the Smart Configurator. Pins are configured by calling the function defined in the source file.

5. Demo Projects

Demo projects include function main() that utilizes the FIT module and its dependent modules (e.g. r_bsp). This FIT module includes the following demo projects.

5.1 irq_demo_rskrx113, irq_demo_rskrx231, irq_demo_rskrx64m, irq_demo_rskrx71m, irq_demo_rskrx65n, irq_demo_rskrx65n_2m, irq_demo_rskrx72m, irq_demo_rskrx671, irq_demo_rskrx113_gcc, irq_demo_rskrx231_gcc, irq_demo_rskrx64m_gcc, irq_demo_rskrx71m_gcc, irq_demo_rskrx65n_gcc, irq_demo_rskrx65n_2m_gcc, irq_demo_rskrx72m_gcc, irq_demo_rskrx671_gcc

These are the demo programs for the IRQ FIT module, designed for the Renesas RSKRX113, RSKRX231, RSKRX64M, RSKRX71M, RSKRX65N, RSKRX65N-2MB, RSKRX72M and RSKRX671 demo boards. The programs demonstrate how to use the R_IRQ_Open API call to configure a port bit as an interrupt input and how to set up a callback function to handle the interrupt. They also demonstrate how to use the R_IRQ_Control API call to reconfigure the interrupt trigger conditions, how to use the R_IRQ_ReadInput API call and how to dereference the callback argument to obtain the interrupt number. IRQ2 (IRQ4 on the RX231, IRQ9 on the RX65N, IRQ13 on the RX65N-2MB, IRQ12 on the RX72M, IRQ10 on the RSKRX671) is chosen as the interrupt and is used to detect key presses on SW2.

All three demo programs operate the same, once the code is compiled and down-loaded to the target board and running, SW2 can be pressed to cause IRQ2 (IRQ4 on the RX231, IRQ9 on the RX65N, IRQ13 on the RX65N-2MB, IRQ12 on the RX72M, IRQ10 on the RSKRX671) interrupts to occur. LED3 will turn on in response to a falling edge when SW2 is pressed and, will turn off in response to a rising edge when SW2 is released.

5.2 Adding a Demo to a Workspace

Demo projects are found in the FITDemos subdirectory of the distribution file for this application note. To add a demo

project to a workspace, select *File >> Import >> General >> Existing Projects into Workspace*, then click "Next". From the Import Projects dialog, choose the "Select archive file" radio button. "Browse" to the FITDemos subdirectory, select the desired demo zip file, then click "Finish".

5.3 Downloading Demo Projects

Demo projects are not included in the RX Driver Package. When using the demo project, the FIT module needs to be downloaded. To download the FIT module, right click on this application note and select "Sample Code (download)" from the context menu in the *Smart Browser* >> *Application Notes* tab.

6. Appendices

6.1 Confirmed Operation Environment

This section describes confirmed operation environment for the IRQ FIT module.

Table 6.1 Confirmed Operation Environment (Rev.4.80)

Item	Contents
Integrated development	Renesas Electronics e ² studio Version 2025-10
environment	IAR Embedded Workbench for Renesas RX 5.10.1
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.07.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99
	GCC for Renesas RX 8.3.0.202411
	Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99
	Linker option: The following user defined option should be added to the default settings of the integrated development environment, if "Optimize size (-Os)" is used:
	-WI,no-gc-sections
	This is to work around a GCC linker issue whereby the linker erroneously discard interrupt functions declared in FIT peripheral module
	IAR C/C++ Compiler for Renesas RX version 5.10.1
	Compiler option: The default settings of the integrated development environment.
Endian	Big endian/Little endian
Revision of the module	Rev.4.80
Board used	Custom board (Target device: R5F526TAExNH)

Table 6.2 Confirmed Operation Environment (Rev.4.71)

Item	Contents
Integrated development	Renesas Electronics e ² studio Version 2025-01
environment	IAR Embedded Workbench for Renesas RX 5.10.1
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.07.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99
	GCC for Renesas RX 8.3.0.202411
	Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99
	Linker option: The following user defined option should be added to the default settings of the integrated development environment, if "Optimize size (-Os)" is used:
	-WI,no-gc-sections
	This is to work around a GCC linker issue whereby the linker erroneously discard interrupt functions declared in FIT peripheral module
	IAR C/C++ Compiler for Renesas RX version 5.10.1
	Compiler option: The default settings of the integrated development
	environment.
Endian	Big endian/Little endian
Revision of the module	Rev.4.71
Board used	-

Table 6.3 Confirmed Operation Environment (Rev.4.70)

Item	Contents
Integrated development	Renesas Electronics e ² studio Version 2024-10
environment	IAR Embedded Workbench for Renesas RX 5.10.1
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.06.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99
	GCC for Renesas RX 8.3.0.202411 Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99
	Linker option: The following user defined option should be added to the default settings of the integrated development environment, if "Optimize size (-Os)" is used: -WI,no-gc-sections
	This is to work around a GCC linker issue whereby the linker erroneously discard interrupt functions declared in FIT peripheral module
	IAR C/C++ Compiler for Renesas RX version 5.10.1
	Compiler option: The default settings of the integrated development environment.
Endian	Big endian/Little endian
Revision of the module	Rev.4.70
Board used	Renesas Starter Kit+ for RX72N (product No.: RTK5572Nxxxxxxxxxxx)

Table 6.4 Confirmed Operation Environment (Rev.4.60)

Item	Contents
Integrated development	Renesas Electronics e ² studio Version 2024-07
environment	IAR Embedded Workbench for Renesas RX 5.10.1
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.06.00
	Compiler option: The following option is added to the default settings of the
	integrated development environment.
	-lang = c99
	GCC for Renesas RX 8.3.0.202405
	Compiler option: The following option is added to the default settings of the
	integrated development environment.
	-std=gnu99
	Linker option: The following user defined option should be added to the
	default settings of the integrated development environment, if "Optimize size
	(-Os)" is used:
	-WI,no-gc-sections
	This is to work around a GCC linker issue whereby the linker erroneously
	discard interrupt functions declared in FIT peripheral module
	IAR C/C++ Compiler for Renesas RX version 5.10.1
	Compiler option: The default settings of the integrated development
	environment.
Endian	Big endian/Little endian
Revision of the module	Rev.4.60
Board used	Evaluation Kit for RX261 (product No.: RTK5EK2610S00011BJ)
	Renesas Solution Starter Kit for RX23E-B (product No.:
	RTK0ES1001C00001BJ)
	Renesas Flexible Motor Control Kit for RX26T (Part Number:
	RTK0EMXE70S00020BJ)
	Renesas Starter Kit for RX113 (product No.: R0K505113CxxxBE)
	Renesas Starter Kit for RX231 (product No.: R0K505231SxxxBE)
	Renesas Starter Kit for RX64M (product No.: R0K50564MxxxxBE)
	Renesas Starter Kit+ for RX65N-2MB (product No.: RTK50565N2CxxxxxBR)
	Renesas Starter Kit+ for RX671 (product No.: RTK55671EDCxxxxxBJ)
	Renesas Starter Kit for RX71M (product No.: R0K50571MCxxxBE)
	Renesas Starter Kit+ for RX72M (product No.: RTK5572MNDCxxxxxBJ)
	Renesas Starter Kit for RX660 (product No: RTK556609HCxxxxxBJ)
	Renesas Starter Kit for RX66T (product No: RTK50566T0SxxxxxBE)
	Renesas Starter Kit+ for RX140 (product No.: RTK5RX140xxxxxxxxxx)
	Renesas Solution Starter Kit+ for RX23E-A (product No.:
	RTK0ESXBxxxxxxxxxxx)
	Renesas Starter Kit+ for RX72N (product No.: RTK5572Nxxxxxxxxxx) RX13T CPU Card (product No.: RTK0EMXA10C00000BJ)
	Renesas Solution Starter Kit for RX23W (product No.: RTK5523Wxxxxxxxxxx
	· ·
	Renesas Starter Kit for RX72T (product No.: RTK5572Txxxxxxxxxxx) Renesas Starter Kit+ for RX130-512KB (product No.: RTK5051308CxxxxxBR
	Renesas Starter Kit+ for RX130-312KB (product No.: RTK3031306CXXXXXBK) Renesas Starter Kit for RX24T (product No.: RTK500524TSxxxxxBE)
	Renesas Starter Kit for RX241 (product No.: RTK50052415xxxxxBE)
	Renesas Starter Kit for RX240 (product No.: RTK50052405XXXXBE)
	Renesas Starter Kit for RX111 (product No.: R1K50052313xxxxxBE)
	Renesas Starter Kit for RX111 (product No.: R0K5051115xxxxx)
	Target Board for RX66N (product No.: RTK5RX66N0C00000BJ)
	Custom board (Target device: R5F52306ADFP)
	Custom board (Target device: R5F52506ADFF) Custom board (Target device: R5F5651EHxLC)
	Gustoffi board (Target device. NJFJ00 TETIALO)

Table 6.5 Confirmed Operation Environment (Rev.4.50)

Item	Contents
Integrated development	Renesas Electronics e ² studio Version 2024-07
environment	IAR Embedded Workbench for Renesas RX 5.10.1
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.06.00 Compiler option: The following option is added to the default settings of the integrated development environment. -lang = c99
	GCC for Renesas RX 8.3.0.202405
	Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99
	Linker option: The following user defined option should be added to the default settings of the integrated development environment, if "Optimize size (-Os)" is used:
	-WI,no-gc-sections
	This is to work around a GCC linker issue whereby the linker erroneously discard interrupt functions declared in FIT peripheral module
	IAR C/C++ Compiler for Renesas RX version 5.10.1
	Compiler option: The default settings of the integrated development
	environment.
Endian	Big endian/Little endian
Revision of the module	Rev.4.50
Board used	Evaluation Kit for RX261 (product No.: RTK5EK2610S00011BJ)

Table 6.6 Confirmed Operation Environment (Rev.4.40)

Item	Contents
Integrated development	Renesas Electronics e ² studio Version 2023-04
environment	IAR Embedded Workbench for Renesas RX 4.20.3
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.05.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99
	GCC for Renesas RX 8.3.0.202204
	Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99
	Linker option: The following user defined option should be added to the default settings of the integrated development environment, if "Optimize size (-Os)" is used: -WI,no-gc-sections
	This is to work around a GCC linker issue whereby the linker erroneously discard interrupt functions declared in FIT peripheral module
	IAR C/C++ Compiler for Renesas RX version 4.20.3
	Compiler option: The default settings of the integrated development environment.
Endian	Big endian/Little endian
Revision of the module	Rev.4.40
Board used	Renesas Solution Starter Kit for RX23E-B (product No.: RTK0ES1001C00001BJ)

Table 6.7 Confirmed Operation Environment (Rev.4.30)

Item	Contents
Integrated development	Renesas Electronics e ² studio Version 2022-10
environment	IAR Embedded Workbench for Renesas RX 4.20.3
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.05.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99
	GCC for Renesas RX 8.3.0.202204 Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99 Linker option: The following user defined option should be added to the default settings of the integrated development environment, if "Optimize size (-Os)" is used: -WI,no-gc-sections This is to work around a GCC linker issue whereby the linker erroneously
	discard interrupt functions declared in FIT peripheral module IAR C/C++ Compiler for Renesas RX version 4.20.3 Compiler option: The default settings of the integrated development environment.
Endian	Big endian/Little endian
Revision of the module	Rev.4.30
Board used	Renesas Flexible Motor Control Kit for RX26T (Part Number: RTK0EMXE70S00020BJ)

Table 6.8 Confirmed Operation Environment (Rev.4.20)

Contents
Renesas Electronics e ² studio Version 2022-07
IAR Embedded Workbench for Renesas RX 4.20.3
Renesas Electronics C/C++ Compiler Package for RX Family V3.04.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99
GCC for Renesas RX 8.3.0.202104
Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99
Linker option: The following user defined option should be added to the default settings of the integrated development environment, if "Optimize size (-Os)" is used: -WI,no-gc-sections
This is to work around a GCC linker issue whereby the linker erroneously discard interrupt functions declared in FIT peripheral module
IAR C/C++ Compiler for Renesas RX version 4.20.3
Compiler option: The default settings of the integrated development environment.
Big endian/Little endian
Rev.4.20
Renesas Starter Kit for RX113 (product No.: R0K505113CxxxBE) Renesas Starter Kit for RX231 (product No.: R0K505231SxxxBE) Renesas Starter Kit for RX64M (product No.: R0K50564MxxxxBE) Renesas Starter Kit+ for RX65N (product No.: RTK5005651CxxxxxBE) Renesas Starter Kit+ for RX65N-2MB (product No.: RTK50565N2CxxxxxBR) Renesas Starter Kit+ for RX671 (product No.: RTK55671EDCxxxxxBJ) Renesas Starter Kit for RX71M (product No.: R0K50571MCxxxxBE) Renesas Starter Kit+ for RX72M (product No.: RTK5572MNDCxxxxxBJ)

Table 6.9 Confirmed Operation Environment (Rev.4.10)

Item	Contents
Integrated development	Renesas Electronics e ² studio Version 2022-04
environment	IAR Embedded Workbench for Renesas RX 4.20.3
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.04.00 Compiler option: The following option is added to the default settings of the integrated development environment. -lang = c99
	GCC for Renesas RX 8.3.0.202104
	Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99
	Linker option: The following user defined option should be added to the default settings of the integrated development environment, if "Optimize size (-Os)" is used: -WI,no-gc-sections
	This is to work around a GCC linker issue whereby the linker erroneously discard interrupt functions declared in FIT peripheral module
	IAR C/C++ Compiler for Renesas RX version 4.20.3
	Compiler option: The default settings of the integrated development
	environment.
Endian	Big endian/Little endian
Revision of the module	Rev.4.10
Board used	Renesas Starter Kit for RX660 (product No: RTK556609HCxxxxxBJ)

Table 6.10 Confirmed Operation Environment (Rev.4.00)

Item	Contents
Integrated development	Renesas Electronics e ² studio Version 2021-10
environment	IAR Embedded Workbench for Renesas RX 4.20.3
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.04.00 Compiler option: The following option is added to the default settings of the integrated development environment. -lang = c99
	GCC for Renesas RX 8.3.0.202104 Compiler option: The following option is added to the default settings of the integrated development environment. -std=gnu99
	Linker option: The following user defined option should be added to the default settings of the integrated development environment, if "Optimize size (-Os)" is used: -WI,no-gc-sections
	This is to work around a GCC linker issue whereby the linker erroneously discard interrupt functions declared in FIT peripheral module
	IAR C/C++ Compiler for Renesas RX version 4.20.3
	Compiler option: The default settings of the integrated development
	environment.
Endian	Big endian/Little endian
Revision of the module	Rev.4.00
Board used	Renesas Starter Kit for RX66T (product No: RTK50566T0SxxxxxBE)

Table 6.11 Confirmed Operation Environment (Rev.3.90)

Item	Contents
Integrated development	Renesas Electronics e ² studio Version 2021-07
environment	IAR Embedded Workbench for Renesas RX 4.20.3
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.03.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99
	GCC for Renesas RX 8.3.0.202004
	Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99
	Linker option: The following user defined option should be added to the default settings of the integrated development environment, if "Optimize size (-Os)" is used:
	 -WI,no-gc-sections This is to work around a GCC linker issue whereby the linker erroneously discard interrupt functions declared in FIT peripheral module
	IAR C/C++ Compiler for Renesas RX version 4.20.3
	Compiler option: The default settings of the integrated development
Endian	environment.
Endian Devision of the module	Big endian/Little endian
Revision of the module	Rev.3.90
Board used	Renesas Starter Kit+ for RX671 (product No.: RTK55671xxxxxxxxxxx)

Item	Contents
Integrated development	Renesas Electronics e ² studio Version 2021-07
environment	IAR Embedded Workbench for Renesas RX 4.20.3
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.03.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99
	GCC for Renesas RX 8.3.0.202004 Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99 Linker option: The following user defined option should be added to the default settings of the integrated development environment, if "Optimize size (-Os)" is used: -WI,no-gc-sections This is to work around a GCC linker issue whereby the linker erroneously discard interrupt functions declared in FIT peripheral module
	IAR C/C++ Compiler for Renesas RX version 4.20.3 Compiler option: The default settings of the integrated development environment.
Endian	Big endian/Little endian
Revision of the module	Rev.3.80
Board used	Renesas Starter Kit+ for RX140 (product No.: RTK5RX140xxxxxxxxxx) Renesas Starter Kit+ for RX671 (product No.: RTK55671xxxxxxxxxxx) Renesas Starter Kit+ for RX65N (product No.: RTK50565NCxxxxxBE) Renesas Starter Kit+ for RX72N (product No.: RTK5572Nxxxxxxxxxxx)

Table 6.13 Confirmed Operation Environment (Rev.3.70)

Item	Contents
Integrated development	Renesas Electronics e ² studio Version 2021-07
environment	IAR Embedded Workbench for Renesas RX 4.20.3
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.03.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99
	GCC for Renesas RX 8.3.0.202004
	Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99
	Linker option: The following user defined option should be added to the default settings of the integrated development environment, if "Optimize size (-Os)" is used:
	-WI,no-gc-sections
	This is to work around a GCC linker issue whereby the linker erroneously discard interrupt functions declared in FIT peripheral module
	IAR C/C++ Compiler for Renesas RX version 4.20.3
	Compiler option: The default settings of the integrated development
	environment.
Endian	Big endian/Little endian
Revision of the module	Rev.3.70
Board used	Renesas Starter Kit+ for RX671 (product No.: RTK55671xxxxxxxxxx)

Table 6.14 Confirmed Operation Environment (Rev.3.60)

Item	Contents
Integrated development environment	Renesas Electronics e ² studio Version 7.8.0
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.02.00 Compiler option: The following option is added to the default settings of the integrated development environment. -lang = c99
	GCC for Renesas RX 8.3.0.201904 Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99
	Linker option: The following user defined option should be added to the default settings of the integrated development environment, if "Optimize size (-Os)" is used: -WI,no-gc-sections
	This is to work around a GCC linker issue whereby the linker erroneously discard interrupt functions declared in FIT peripheral module
Endian	Little endian
Revision of the module	Rev.3.60
Board used	Renesas Starter Kit+ for RX72M (product No.: RTK5572Mxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxx

Table 6.15 Confirmed Operation Environment (Rev.3.50)

Item	Contents
Integrated development	Renesas Electronics e ² studio Version 7.7.0
environment	IAR Embedded Workbench for Renesas RX 4.12.1
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.02.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99
	GCC for Renesas RX 8.3.0.201904 Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99 Linker option: The following user defined option should be added to the
	default settings of the integrated development environment, if "Optimize size (-Os)" is used: -WI,no-gc-sections
	This is to work around a GCC linker issue whereby the linker erroneously discard interrupt functions declared in FIT peripheral module
	IAR C/C++ Compiler for Renesas RX version 4.12.1
	Compiler option: The default settings of the integrated development
	environment.
Endian	Big endian/little endian
Revision of the module	Rev.3.50
Board used	Renesas Solution Starter Kit+ for RX23E-A (product No.: RTK0ESXBxxxxxxxxxx)

Table 6.16 Confirmed Operation Environment (Rev.3.40)

Item	Contents
Integrated development	Renesas Electronics e ² studio Version 7.7.0
environment	IAR Embedded Workbench for Renesas RX 4.12.1
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.01.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99
	GCC for Renesas RX 4.8.4.201902
	Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99
	Linker option: The following user defined option should be added to the default settings of the integrated development environment, if "Optimize size (-Os)" is used:
	-WI,no-gc-sections
	This is to work around a GCC linker issue whereby the linker erroneously discard interrupt functions declared in FIT peripheral module
	IAR C/C++ Compiler for Renesas RX version 4.12.1
	Compiler option: The default settings of the integrated development
	environment.
Endian	Big endian/little endian
Revision of the module	Rev.3.40
Board used	Renesas Starter Kit+ for RX72N (product No.: RTK5572Nxxxxxxxxxxx).

Table 6.17 Confirmed Operation Environment (Rev.3.30)

Item	Contents
Integrated development	Renesas Electronics e ² studio Version 7.7.0
environment	IAR Embedded Workbench for Renesas RX 4.12.1
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.01.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99
	GCC for Renesas RX 4.8.4.201902
	Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99
	Linker option: The following user defined option should be added to the default settings of the integrated development environment, if "Optimize size (-Os)" is used:
	-WI,no-gc-sections
	This is to work around a GCC linker issue whereby the linker erroneously discard interrupt functions declared in FIT peripheral module
	IAR C/C++ Compiler for Renesas RX version 4.12.1
	Compiler option: The default settings of the integrated development environment.
Endian	Big endian/little endian
Revision of the module	Rev.3.30
Board used	RX13T CPU Card (product No.: RTK0EMXA10C00000BJ)

Table 6.18 Confirmed Operation Environment (Rev.3.20)

Item	Contents
Integrated development	Renesas Electronics e ² studio Version 7.5.0
environment	IAR Embedded Workbench for Renesas RX 4.12.1
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.01.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99
	GCC for Renesas RX 4.8.4.201902
	Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99
	Linker option: The following user defined option should be added to the default settings of the integrated development environment, if "Optimize size (-Os)" is used:
	-WI,no-gc-sections
	This is to work around a GCC linker issue whereby the linker erroneously discard interrupt functions declared in FIT peripheral module
	IAR C/C++ Compiler for Renesas RX version 4.12.1
	Compiler option: The default settings of the integrated development
	environment.
Endian	Big endian/little endian
Revision of the module	Rev.3.20
Board used	Renesas Starter Kit+ for RX72M (product No.: RTK5572Mxxxxxxxxxx)

Table 6.19 Confirmed Operation Environment (Rev.3.10)

Item	Contents
Integrated development environment	Renesas Electronics e ² studio Version 7.5.0
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.01.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99
Endian	Big endian/little endian
Revision of the module	Rev.3.10
Board used	Renesas Solution Starter Kit for RX23W (product No.: RTK5523Wxxxxxxxxxx)

Table 6.20 Confirmed Operation Environment (Rev.3.00)

Item	Contents
Integrated development	Renesas Electronics e ² studio Version 7.4.0
environment	IAR Embedded Workbench for Renesas RX 4.10.1
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.01.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99
	GCC for Renesas RX 4.8.4.201803 Compiler option: The following option is added to the default settings of the integrated development environment. -std=gnu99
	Linker option: The following user defined option should be added to the default settings of the integrated development environment, if "Optimize size (-Os)" is used: -WI,no-gc-sections
	This is to work around a GCC linker issue whereby the linker erroneously discard interrupt functions declared in FIT peripheral module
	IAR C/C++ Compiler for Renesas RX version 4.10.1
	Compiler option: The default settings of the integrated development environment.
Endian	Big endian/little endian
Revision of the module	Rev.3.00
Board used	Renesas Starter Kit+ for RX65N-2MB (product No.: RTK50565Nxxxxxxxxxx)

Table 6.21 Confirmed Operation Environment (Rev.2.40)

Item	Contents
Integrated development environment	Renesas Electronics e2 studio version 7.3.0
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.01.00
	Compiler option: The following option is added to the default settings of the
	integrated development environment.
	-lang = c99
Endian	Big endian/little endian
Revision of the module	Rev.2.40
Board used	Renesas Starter Kit for RX72T (product No.: RTK5572Txxxxxxxxxxx)

Table 6.22 Confirmed Operation Environment (Rev.2.31)

Item	Contents
Integrated development environment	Renesas Electronics e ² studio Version 7.3.0
	Renesas Electronics C/C++ Compiler Package for RX Family V3.01.00
C compiler	Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99
Endian	Big endian/little endian
Revision of the module	Rev.2.31
Board used	Renesas Starter Kit for RX66T (product No.: RTK50566T0SxxxxxBE)
	Renesas Starter Kit+ for RX 65N-2MB (product No.: RTK50565N2CxxxxxBR)
	Renesas Starter Kit+ for RX130-512KB (product No.: RTK5051308CxxxxxBR)

Table 6.23 Confirmed Operation Environment (Rev.2.30)

Item	Contents
Integrated development environment	Renesas Electronics e ² studio Version 7.0.0
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.00.00
	Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99
Endian	Big endian/little endian
Revision of the module	Rev.2.30
Board used	Renesas Starter Kit for RX66T (product No.: RTK50566T0SxxxxxBE)
	Renesas Starter Kit+ for RX 65N-2MB (product No.: RTK50565N2CxxxxxBR)
	Renesas Starter Kit+ for RX130-512KB (product No.: RTK5051308CxxxxxBR)

Table 6.24 Confirmed Operation Environment (Rev.2.21)

Item	Contents
Integrated development environment	Renesas Electronics e ² studio Version 6.0.0
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V2.07.00
	Compiler option: The following option is added to the default settings of the integrated development environment.
	-lang = c99
Endian	Big endian/little endian
Revision of the module	Rev.2.21
Board used	Renesas Starter Kit+ for RX 65N-2MB (product No.: RTK50565N2CxxxxxBR)
	Renesas Starter Kit+ for RX130-512KB (product No.: RTK5051308CxxxxxBR)

Table 6.25 Confirmed Operation Environment (Rev.2.20)

Item	Contents		
Integrated development environment	Renesas Electronics e ² studio Version 6.0.0		
	Renesas Electronics C/C++ Compiler Package for RX Family V2.07.00		
C compiler	Compiler option: The following option is added to the default settings of the integrated development environment.		
	-lang = c99		
Endian	Big endian/little endian		
Revision of the module	Rev.2.20		
Board used	Renesas Starter Kit+ for RX 65N-2MB (product No.: RTK50565N2CxxxxxBR)		
	Renesas Starter Kit+ for RX130-512KB (product No.: RTK5051308CxxxxxBR)		

6.2 Troubleshooting

- (1) Q: I have added the FIT module to the project and built it. Then I got the error: Could not open source file "platform.h".
 - A: The FIT module may not be added to the project properly. Check if the method for adding FIT modules is correct with the following documents:
 - Using CS+:

Application note "Adding Firmware Integration Technology Modules to CS+ Projects (R01AN1826)"

Using e² studio:

Application note "Adding Firmware Integration Technology Modules to Projects (R01AN1723)"

When using a FIT module, the board support package FIT module (BSP module) must also be added to the project. Refer to the application note "Board Support Package Module Using Firmware Integration Technology (R01AN1685)".

- (2) Q: I have added the FIT module to the project and built it. Then I got the error: This MCU is not supported by the current r_irq_rx module.
 - A: The FIT module you added may not support the target device chosen in your project. Check the supported devices of added FIT modules.
- (3) Q: I have added the FIT module to the project and built it. Then I got an error for when the configuration setting is wrong.
 - A: The setting in the file "r_irq_rx_config.h" may be wrong. Check the file "r_irq_rx_config.h". If there is a wrong setting, set the correct value for that. Refer to 2.8, Configuration Overview for details.
- (4) Q: Interrupt does not occur.
 - A: The pin setting may not be performed correctly. When using this FIT module, the pin setting must be performed. Refer to 4. Pin Setting for details.

7. Reference Documents

User's Manual: Hardware

The latest version can be downloaded from the Renesas Electronics website.

Technical Update/Technical News

The latest information can be downloaded from the Renesas Electronics website.

User's Manual: Development Tools

RX Family Compiler CC-RX User's Manual (R20UT3248)

The latest versions can be downloaded from the Renesas Electronics website.

Related Technical Updates

This module reflects the content of the following technical updates. None

R01AN1668EJ0480 Rev.4.80

Revision History

		Description	on
Rev.	Date	Page	Summary
1.00	Nov 15, 2013		First edition issued
1.20	April 10, 2014	1	Added RX110 to list of tested MCUs
		4	Added sections 1.2, 1.3 callback functions usage
			Updated Colophon to 4.0
1.30	July 23, 2014	Various	Added mention of RX64M in supported MCUs, added code
			size information, updated format.
1.40	Jan 08,2015	Various	Updated to current template.
			Added support for the RX113 Group.
1.50	Mar 24,2015	_	Added support for the RX71M Group.
1.60	June 30,2015	_	Added support for the RX231 Group.
1.70	Sep 30,2015	_	Added support for the RX23T Group.
		_	Fixed typo in the Return value:
			IRQ_ERR_NOT_OPEN -> IRQ_ERR_NOT_OPENED
		7	Updated code sizes in 2.8 Code Size for the RX23T Group.
1.80	Oct 1, 2015		Added support for the RX130 Group.
		7	Updated code sizes in 2.8 Code Size for the RX130 Group.
1.90	Dec 1, 2015	_	Added support for the RX230 and the RX24T Groups.
		1, 9	Changed the document number for the "Board Support
			Package Firmware Integration Technology Module" application
			note.
		5	Changed the description in section 2.
		7	Updated 2.8 Code Size for the RX230 and the RX24T Groups.
		17	Added "4. Demo Projects".
1.91	June 15, 2016	17	Added RSKRX64M to "4. Demo Projects".
		18	Added "Related Technical Updates".
2.00	Oct 1, 2016		Added support for the RX65N Group.
		7, 8	Changed 2.8 Code Size for the tabular format of Code Size.
			Updated 2.8 Code Size for the RX65N Group.
		18	Added "4. Pin Setting".
2.10	Feb 28, 2017		Added support for the RX24U Group.
		7	Updated 2.8 Code Size for the RX24U Group.
2.20	July 21, 2017		Added support for the RX130-512KB and RX65N-2MB.
		5	Added RXC v2.07.00 to "2.4 Supported Toolchains".
		6	Added "2.5 Interrupt Vector"
		11	Added "2.12 Adding the FIT Module to Your Project".
		19	Added "4. Pin Setting".
2.21	Oct 31, 2017	20	Added RSKRX65N, RSKRX65N-2MB to "5. Demo Projects"
		20	Added 5.3 Downloading Demo Project
		21	Added 6. Appendices

		Description	1
Rev.	Date	Page	Summary
2.30	Sep 28, 2018	_	Changed the structure of macros in r_irq_rx_config.h,
			r_irq_rx_private.h
		1, 7	Added support for the RX66T.
		4	Added instruction on how to comment/uncomment macros
		8	when Smart Configurator or FIT Configurator is used. In "Configuration options in r_irq_rx_config.h" table,
		O	removed IRQ_CFG_USE_IRQn 0,
			changed IRQ PORT IRQn to IRQ PORT IRQn PORT
			changed IRQ_PORT_BIT_IRQn to IRQ_PORT_IRQn_BIT
		10	Added code size corresponding to RX66T
		26	6.1 Confirmed Operation Environment:
			Added table for Rev.2.30
2.31	Nov 16, 2018	_	Added document number in XML
		26	Changed Renesas Starter Kit Product No for RX66T.
			Added table for Rev.2.31
2.40	Feb 01, 2019	Program	Added support for the RX72T
		1, 7, 11	Added support for the RX72T
		16-23	Removed 'Reentrant' description in each API function.
		26	6.1 Confirmed Operation Environment:
0.00	M 00 40		Added table for Rev.2.40
3.00	May.20.19		Supported the following compilers:
			GCC for Renesas RXIAR C/C++ Compiler for Renesas RX
		1	Deleted the RX210, and RX63N in Target Devices for end of
		'	update these devices.
			Added the section of Target compilers.
			Deleted related documents.
		6	2.2 Software Requirements
			Requires r_bsp v5.20 or higher
		9-14	Updated the section of 2.8 Code Size
		7	2.4 Interrupt Vector: Deleted RX210, RX63N
		32	Table 6.1 Confirmed Operation Environment:
			Added table for Rev.3.00
		36	Deleted the section of Website and Support.
		Program	Changed bellow for support GCC and IAR compiler:
			Deleted the inline expansion of the R_IRQ_GetVersion
			function. 2. Replaced nop with the intrinsic functions of BSP.
			3. Replaced the declaration of interrupt functions with the
			macro definition of BSP.
3.10	Jun.28.19	1, 7	Added support for RX23W
0.10	0411120110	10	Added code size corresponding to RX23W
		32	6.1 Confirmed Operation Environment:
			Added Table for Rev.3.10
		Program	Added support for RX23W
3.20	Aug.15.19	1, 7	Added support for RX72M
	9 9	11, 14, 17	Added code size corresponding to RX72M
		32	6.1 Confirmed Operation Environment:
			Added Table for Rev.3.20
			Table 6.2: Corrected board name for RX23W
		Program	Added support for RX72M
		Program	Auded Support for IVV/ ZIM

		Description	n
Rev.	Date	Page	Summary
3.30	Nov.25.2019	1, 7	Added support for RX13T
		6	2.3 Limitations
			Added limitations
		12, 13, 16	Added code size corresponding to RX13T
		33	6.1 Confirmed Operation Environment:
			Added Table for Rev.3.30
		Program	Added support for RX13T
			Changed the comment of API functions to the doxygen style.
3.40	Dec.30.2019	1, 7	Added support for RX66N and RX72N
		12, 14, 16, 18, 20	Added code size corresponding to RX66N and RX72N
		35	6.1 Confirmed Operation Environment:
		_	Added Table for Rev.3.40
		Program	Added support for RX66N and RX72N
3.50	Mar.31.2020	1, 8	Added support for RX23E-A
		13, 14, 18, 22	Added code size corresponding to RX23E-A
		37	6.1 Confirmed Operation Environment:
		_	Added Table for Rev.3.50
0.00		Program	Added support for RX23E-A
3.60	Jun.30.20	36	Updated and added new demo project
		0.7	Added RSKRX72M to "5. Demo Projects".
		37	6.1 Confirmed Operation Environment:
		Drogram	Added Table for Rev.3.60
3.70	Mar.31.21	Program	Updated and added new demo project Added support for RX671.
3.70	Wai.31.21	1, 8 6	Added 1.3.1 Using FIT IRQ module in C++ project.
		14, 18, 22	Added code size corresponding to RX671.
		37	6.1 Confirmed Operation Environment:
		01	Added Table for Rev. 3.70.
		Program	Added support for RX671
3.80	Apr.15.21	1, 8	Added support for RX140.
0.00		14, 19, 24	Added code size corresponding to RX140.
		6, 37	Added R_IRQ_IRClear() function to clear IR flag.
		40	6.1 Confirmed Operation Environment:
			Added Table for Rev. 3.80.
		Program	Added support for RX140.
		Ü	Added CS+ support for demo project.
			Added R_IRQ_IRClear() function to clear IR flag.
3.90	Sep.13.21	39	Added RSKRX671 to "5. Demo Projects".
	·	40	6.1 Confirmed Operation Environment:
			Added Table for Rev. 3.90.
		Program	Updated and added new demo projects
4.00	Mar.14.22	40	6.1 Confirmed Operation Environment:
			Added Table for Rev. 4.00.
		Program	Added support for RX66T-48Pin.
4.10	Mar.31.22	1, 8	Added support for RX660
		15, 20, 25	Added code size corresponding to RX660.
		41	6.1 Confirmed Operation Environment:
			Added Table for Rev. 4.10.
		Program	Added support for RX660.

		Description	1
Rev.	Date	Page	Summary
4.20	Jun.28.22	41	6.1 Confirmed Operation Environment:
			Added Table for Rev. 4.20.
		Program	Updated demo projects
4.30	Aug.15.22	1, 8	Added support for RX26T.
		15, 20, 25	Added code size corresponding to RX26T.
		41	6.1 Confirmed Operation Environment:
			Added Table for Rev. 4.30.
		Program	Added support for RX26T.
4.40	May.29.23	1, 8	Added support for RX23E-B.
		16, 22, 28	Added code size corresponding to RX23E-B.
		5, 31, 42	Deleted the description of FIT configurator from "1.3 Using the FIT IRQ Module", "2.13 Adding the FIT Module to Your Project" and "4. Pin Settings".
		44	6.1 Confirmed Operation Environment:
			Added Table for Rev. 4.40.
		Program	Added support for RX23E-B.
			Deleted the description of FIT configurator.
4.50	Jun.28.24	1, 8	Added support for RX261, RX260.
		16, 22, 28	Added code size corresponding to RX261, RX260.
		44	6.1 Confirmed Operation Environment:
			Added Table for Rev. 4.50.
		Program	Added support for RX261, RX260.
			Updated constraint in MDF file to disable configuration of
			unsupported channels for RX260, RX261.
			Updated .ftl file to set register value using BYTE format.
4.60	Nov.01.24	44	6.1 Confirmed Operation Environment:
		_	Added Table for Rev. 4.60.
		Program	Updated constraint in MDF file to disable configuration of unsupported channels for all devices.
4.70	Dec.31.24	9	Added new macros IRQ_CFG_NESTED_INT_EN_IRQn to support nested interrupt.
		10-12, 16-	2.9 Code Size, amended.
		27	
		44	6.1 Confirmed Operation Environment:
			Added Table for Rev. 4.70.
		Program	Added support nested interrupt.
4.71	Mar.15.25	43	6.1 Confirmed Operation Environment:
			Added Table for Rev. 4.71.
		Program	Updated FIT Disclaimer and Copyright.
4.80	Oct.30.25	43	6.1 Confirmed Operation Environment:
			Added Table for Rev. 4.80.
		Program	Added support for RX26T 32-pin.
			Removed doc folder and updated .rcpc file in FITDemos.

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4 Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan www.renesas.com

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